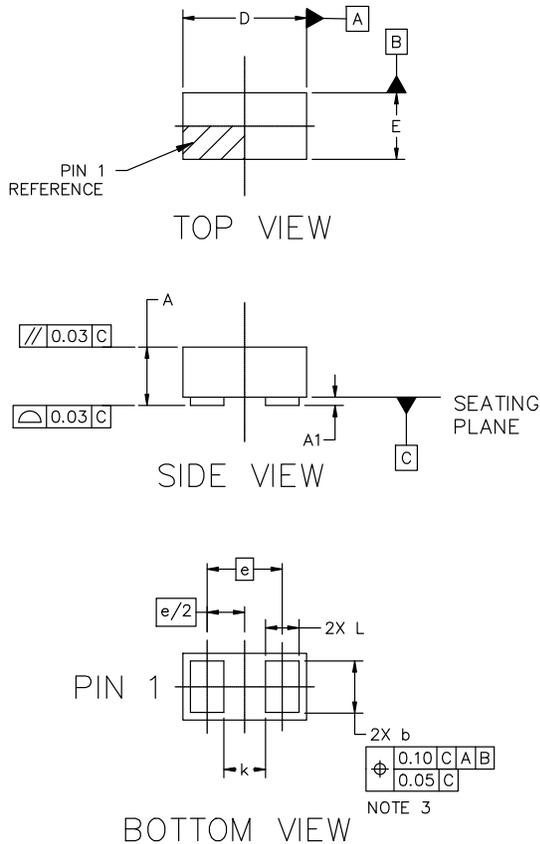




**X4DFN2, 0.44x0.24x0.18, 0.27P**  
**CASE 718AA**  
**ISSUE B**

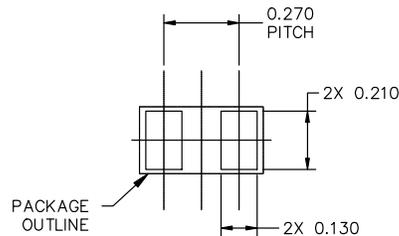
DATE 05 MAR 2025



NOTES:

1. DIMENSIONING AND TOLERANCING AS PER ASME Y14.5M, 2018.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. EXPOSED COPPER ALLOWED AS SHOWN.

MILLIMETERS			
DIM	MIN	NOM	MAX
A	0.150	0.180	0.210
A1	---	---	0.030
b	0.170	0.185	0.200
D	0.415	0.445	0.475
E	0.210	0.240	0.270
e	0.270 BSC		
k	0.125	---	---
L	0.105	0.120	0.135



RECOMMENDED MOUNTING FOOTPRINT

- \* For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

**GENERIC MARKING DIAGRAMS\***



X = Specific Device Code

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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<b>DESCRIPTION:</b>	<b>X4DFN2, 0.44x0.24x0.18, 0.27P</b>	<b>PAGE 1 OF 1</b>

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